WLMIC-Partlist (QA3)

Note:

ITEM	DESCRIPTION	QTY	LOCATION	
WLMIC_FAS1 (WLMIC_FAS2)				
Receiver partlist	WIRELESS MICROPHONE RECEIVER ASSEMBLY			
1	PCB DS FR4 15X21X1.2MM MINI USB NO-Halog	1	PCB	
2	Tach Switch TC-0204X-A14 WEALTH	1	SW1	
3	USB JACKET MINI 5 PIN TYPE B F	1	USB	
4	SOLDER WIRE 0.81MM 96SC CRYSTAL 511 MULT	0.658G		
5		1		
Receiver partlist	WIRELESS MICROPHONE RECEIVER SMT			
1	CHIP TRANSISTOR LMBT4401 LT1G SOT-23 LRC	1	Q1	
2	DES:PMOS FET LP4101LT1G SOT-23 LRC	1	Q2	
3	IC nRF24Z1 QFN-36 NORDIC	2	U1,U6	
4	LDO PT5108X23E-33 3.3V LEAD FREE POWTECH	1	U2	
second	LDO MM3293DNRE 3.3V SOT-23-5 MISUMI	0	U2	
5	24BIT 2CH D/A CONVERTER AK4386ET TSSOP-16	2	U3,U4	
6	2CH A/D CONVERTER AK5371AVQ LQFP-48 AKM	1	U5	
7	EEPROM IS93C46D-2GRLI-TR SOIC	1	U7	
8	IC PIC16F57T-I/SS030 SSOP-28 MICROCHIP	1	U8	
9	IC 24AA04T-I/OT SOT23-5 （EEPROM） MICROCHIP	1	U9	
10	RED SMD 0603 CHIP LED LAMP	1	D1	
Second	LED RED SMD 0603 FC-1608SXK(5)-620D08 NATIONS	0	D1	
11	LED 19-21/GHC-YR1S2/3T 0603 GREEN GERCHIH	1	D2	
Second	LED FC1608UGK-520D 0603 GREEN NATIONSTAR	0	D2	
12	CHIP RES 1M OHM 0402 5% 1/16W	3	R1,R27,R48	
13	CHIP RES 100 OHM 1% 0402 L&CD/	8	R2,R16,R17,R20,R21,R29,R30,R31	
14	CHIP RES 47K OHM 5% 1/16W 0402	13	R4,R9,R28,R38,R39,R40,R43,R44,R45,R45A,R46,R47,R70	
15	RES OR 5% 50V 0402 LEAD FREE	2	R5,R36	
16	CHIP RES 22K OHM 0603 1/10W 1% RALEC	2	R6,R14	
17	CHIP RES 51K 0402 1% LEAD FREE	1	R7	
18	RES 18K 0402 63mW 5% LEADFREE	1	R8	
19	CHIP RES 56K OHM 5% 1/16W 0402	1	R10	
20	CHIP RES 24 OHM 5% 1/16W 0402	2	R11,R12	
21	RES 1.5K 0402 63mW 5% LEAD FRE	1	R13	
22	CHIP RES 10 OHM 5% 0402 Pb&Cd 1/16W	1	R15	
23	CHIP RES 220 OHM +/-1% 0402	2	R19,R22	
24	CHIP RES 2.2K OHM 1/16W 5%	1	R25	
25	CHIP RES 22K OHM 1/16W 1%	1	R26	
second	RES 22K 0402 63mW 1% LEAD FREE	0	R26	
26	CHIP RES 220K OHM 1/16W 1% 0402 L&Cd FRE	1	R32	
27	CHIP RES 1K OHM 5% 1/16W 0402/	2	R34,R35	
28	CHIP RES 11K OHM 1/16W 1% 0402	1	R37	
29	CHIP RES 10K OHM +/-5% 1/16W 0402	3	R41,R42,R50	
30	CHIP CAP 33nF+-10% 10V X7R 0402	2	C1,C52	
second	CHIP CAP X5R 33NF 10% 10V 0402	0	C1,C52	
31	CAP C0G 15pF 0402 50V +/-5%	4	C2,C3,C24,C25	
32	Chip Cap 2.2NF 50V +/-10% NPO 0603 SAMSUNG	2	C4,C48	
33	Chip Cap 4.7PF 50V +/-5% NPO 0603 SAMSUNG	2	C5,C47	
34	Chip Cap 1.0PF 50V +/-5% NPO 0603 SAMSUNG ROHS/SS259	6	C6,C35,C46,C56,C60,C70	
35	CHIP CAP 10nF 16V X7R 10% 0402L&Cd FREE	5	C8,C51,C66,R18,R23	
36	CHIP CAP 1nF 50V X7R 10% 0402 L&Cd Free	2	C9,C50	
second	CHIP CAP 1nF 50V X7R +/-10% 0402	0	C9,C50	
37	TANT CAP TCSCS1A106MAAR 10UF 10V+-20% 3.2X1	2	C10,C49	
second	TANT CAP TAJA106M010RNJ 10UF 10V +-20% 3.2X1.	0	C10,C49	
38	CAP X5R 100NF 0402 10V +/-10% LEAD FREE	12	C11,C13,C17,C19,C20,C23,C27,C29,C40,C41,C63,C67	
second	CHIP CAP 0.1UF/16V +80-20% 0402 TAIYO YU	0	C11,C13,C17,C19,C20,C23,C27,C29,C40,C41,C63,C67	
39	CHIP CAP 4.7uF 16V X5R 10% 0805	6	C12,C16,C22,C28,C37,C42	
second	CHIP CAP 4.7uF 10V X5R 10% 0805 LMK212BJ475KG-T TAIYO YUDEN	6	C12,C16,C22,C28,C37,C42	
40	Chip Cap 8200PF 50V +/-10% X7R 0402 SAMSUNG	1	C14	
41	Chip Cap 6800PF 50V +/-10% X7R 0402 SAMSUNG	1	C15	
42	CHIP CAP 100pF/50V 0402 10%NP0	3	C18,C21,C64	
43	Chip Cap C0402X5R334K100NT 0.33UF 10V +/-10%	2	C61,C62	
44	Chip Cap 47PF 50V +/-5% COG 0402 SAMSUNG	2	C26,C31	

No.	Description	Qty	Reference
45	Chip Cap 3300PF 50V +/-10% X7R 0402 SAMSUNG	1	C30
46	CHIP CAP 10UF/10V +80-20% 0805 TAIYO YUD	3	C32,C53,C54
47	CHIP CAP 2.2nF+-10% 50V X7R 0402	1	C33
second source	CHIP CAP 2.2nF +/-10% 50V X7R 0402	0	C33
48	CHIP CAP 1UF/10V +80-20% 0603	3	C38,C43,C65
second	CHIP CAP 1UF/16V +80-20% 0603	0	C38,C43,C65
49	CHIP CAP 1.0PF +/-0.1PF NPO 50V 0402 LF,UMK105CG010BW-F	4	C7,C45,C57,C58
50	CAP X5R 1UF 0402 6.3V +/-10% LEAD FREE	1	C59
second	CAP X5R 1uF 0402 6.3V +/-10% L	0	C59
51	CHIP CAP 27pF +/-5% 50V COG	1	C60A
second	CHIP CAP 27pF +-5% 50V COG 0402 UMK105CG270JV-F TAIYO YUDEN	0	C60A
52	CHIP INDUCTOR,2.2NH +/-5% 0402 HK16086N8J-T T	2	L2,L4
53	CHIP INDUCTOR,3.3NH +/-0.3NH 0603 ELJRE3N3DF/	2	L1,L5
54	CHIP INDUCTOR,10NH +-5% 0603 ELJRE10NJFA	2	L3,L6
55		1	PCB
56	CRYSTAL 7B16000042 16MHZ +-10PPM 3.2X5MM SM	1	X1
57	CRYSTAL 11.2896MHZ FC112896S I	1	X2
second	CRYSTAL HC-49S 11.2896MHZ JING	0	X2
58	LEAD FREE SOLDER PASTE SC96LF320AGS88.5		
MIC partlist	**WIRELESS MICROPHONE RED ASSEMBLY**		
1	LED LL-3DRGPWA0-SR D3.0MM RED/GREEN GER CHIH	1	D1&D2
2	ECAP 470UF 10V +-20% 6.3X11 P2.5 CUT-LEAD SAMSON	1	C12
second	ECAP 470UF 10V +-20% 6.3X11 P2.5 CUT-LEAD OCEAN	0	C12
3	PCB DS FR1 1L 20X30X1.0MM TX SWITCH NO-H	1	PCB
4	SLIDE SWITCH MSH-12N05-22-1 CHI FUNG	1	SW
5	Voice coil -54dB DM-10B-NT	1	VOICE COIL
6	SOLDER WIRE 0.81MM 96SC CRYSTAL 511 MULT	0.752G	
7		1	
MIC partlist	**WIRELESS MICROPHONE SMT**		
1	CHIP TRANSISTOR LMBT4401 LT1G SOT-23 LRC	1	Q4
2	DES:PMOS FET LP4101LT1G SOT-23 LRC	1	Q2
3	IC nRF24Z1 QFN-36 NORDIC	1	U1
4	IC PIC16F505T-I/SL040RED SOIC-14 MICROCHIP	1	U2
second	IC PIC16F505T-I/SL SOIC-14 MICROCHIP	0	U2
5	IC NC7SZ00M5X SOT23-5 FAIRCHILD ROHS/SS259	1	U3
6	16BIT MONO A/D CONVERTER AK5700VN QFN-24	1	U5
second	IC AK5701VN -30 +80 DEGREE QFN24 FOR WLMIC	0	U5
7	DIODE LMDL914T1G SOD-323 LEAD FREE LRC	1	D6
8	CHIP RES 1M OHM 0402 5% 1/16W	2	R1,R19
9	CHIP RES 56R OHM 1/16W 5% 0402	4	R2,R14,R16,R17
10	CHIP RES 47K OHM 5% 1/16W 0402	7	R3,R4,R5,R8,R10,R11,R24
11	CHIP RES 22K OHM 0603 1/10W 1% RALEC	1	R6
12	CHIP RES 1K OHM 5% 1/16W 0402/	4	R7,R12,R18,R23
13	CHIP RES 220 OHM +/-1% 0402	1	R13
14	RES OR 5% 50V 0402 LEAD FREE	1	R9
15	CHIP RES 10K OHM +/-5% 1/16W 0402 RALEC	2	R15,R22
16	CHIP RES 220K OHM 1/16W 1% 0402 L&Cd FRE	1	R20
17	CHIP RES 22K OHM 1/16W 1%	1	R21
second	RES 22K 0402 63mW 1% LEAD FREE	0	R21
18	CHIP CAP 33nF+-10% 10V X7R 0402	1	C1
second	CHIP CAP X5R 33NF 10% 10V 0402	0	C1
19	CAP C0G 15pF 0402 50V +/-5%	2	C2,C3
20	Chip Cap 2.2NF 50V +/-10% NPO 0603 SAMSUNG	1	C4
21	Chip Cap 4.7PF 50V +/-5% NPO 0603 SAMSUNG	1	C5
22	Chip Cap 1.0PF 50V +/-5% NPO 0603 SAMSUNG	3	C6,C7,C27
23	CHIP CAP 10nF 16V X7R 10% 0402L&Cd FREE	1	C8
24	CHIP CAP 1nF 50V X7R 10% 0402 L&Cd Free	1	C9
second	CHIP CAP 1nF 50V X7R +/-10% 0402	0	C9
25	TANT CAP TCSCS1A106MAAR 10UF 10V+-20% 3.2X1	1	C10
second	TANT CAP TAJA106M010RNJ 10UF 10V +-20% 3.2X1.	0	C10
26	CAP X5R 100NF 0402 10V +/-10% LEAD FREE	5	C11,C19,C22,C24,C43
second	CHIP CAP 0.1UF/16V +80-20% 0402 TAIYO YU	0	C11,C19,C22,C24,C43
27	Chip Cap 0.1UF 10V +/-10% X7R 0603 SAMSUNG	1	C16
28	CHIP CAP 100pF/50V 0402 10%NP0	3	C18,C28,C30
29	CAP X5R 1UF 0402 6.3V +/-10% LEAD FREE	3	C20,C21,C29
second	CAP X5R 1uF 0402 6.3V +/-10% L	0	C20,C21,C29
30	CHIP CAP 2.2uF 6.3V X5R 10% 06	1	C23
31	CHIP CAP 10UF/10V +80-20% 0805 TAIYO YUD	1	C25
32	CHIP INDUCTOR,2.2NH +/-0.3NH 0402 HK10052N2S-	1	C14
33	CHIP INDUCTOR,3.3NH +/-0.3NH 0603 ELJRE3N3DF/	1	L1
34	CHIP INDUCTOR,6.8NH +/-5% 0603 HK16086N8J-T T	1	L2
35	CHIP INDUCTOR,10NH +-5% 0603 ELJRE10NJFA	1	L3
36	CRYSTAL 7B16000042 16MHZ +-10PPM 3.2X5MM SM	1	X1
37	PCB 4L FR4 71X23X1.6MM WM-MIC(RED TX1) N	1	PCB
38	LEAD FREE SOLDER PASTE SC96LF320AGS88.5	0.06G	